# **BS208**

### **DMOS Transistors (P-Channel)**

### FEATURES

- High breakdown voltage
- High input impedance
- Low gate threshold voltage
- Low drain-source ON resistance
- ♦ High-speed switching
- No minority carrier storage time
- CMOS logic compatible input
- No thermal runaway
- No secondary breakdown
- Specially suited for telephone subsets

#### **MECHANICAL DATA**

**Case:** TO-92 Plastic Package **Weight:** approx. 0.18 g On special request, this transistor is also manufactured in the pin configuration TO-18.

### MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25 °C ambient temperature unless otherwise specified

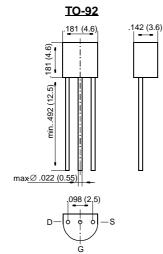
Dimensions in inches and (millimeters)

Symbol	Value	Unit	
-V <sub>DSS</sub>	240	V	
-V <sub>DGS</sub>	240	V	
V <sub>GS</sub>	± 20	V	
-I <sub>D</sub>	200	mA	
P <sub>tot</sub>	0.83 <sup>1)</sup>	W	
Tj	150	°C	
T <sub>S</sub>	-65 to +150	°C	
	-V <sub>DSS</sub> -V <sub>DGS</sub> V <sub>GS</sub> -I <sub>D</sub> P <sub>tot</sub> T <sub>j</sub>	$-V_{DSS}$ 240 $-V_{DGS}$ 240 $V_{GS}$ ± 20 $-I_D$ 200 $P_{tot}$ 0.83 <sup>1)</sup> $T_j$ 150	

#### Inverse Diode

	Symbol	Value	Unit
Max. Forward Current (continuous) at T <sub>amb</sub> = 25 °C	lF	0.75	A
Forward Voltage Drop (typ.) at $V_{GS} = 0$ , $I_F = 0.75$ A, $T_j = 25$ °C	V <sub>F</sub>	0.85	V







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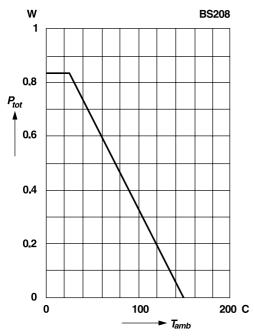
# ELECTRICAL CHARACTERISTICS

	Symbol	Min.	Тур.	Max.	Unit
Drain-Source Breakdown Voltage at $-I_D = 100 \ \mu$ A, V <sub>GS</sub> = 0	-V <sub>(BR)DSS</sub>	240	250	-	V
Gate-Body Leakage Current at $-V_{GS} = 15 \text{ V}, V_{DS} = 0$	-I <sub>GSS</sub>	-	-	10	nA
Drain Cutoff Current at $-V_{DS} = 130 \text{ V}, V_{GS} = 0$ at $-V_{DS} = 70 \text{ V}, -V_{GS} = 0.2 \text{ V}$	-I <sub>DSS</sub> -I <sub>DSX</sub>			1 25	μΑ μΑ
Gate-Source Threshold Voltage at $V_{GS} = V_{DS}$ , $-I_D = 1 \text{ mA}$	-V <sub>GS(th)</sub>	0.8	1.5	2.5	V
Drain-Source ON Resistance at $-V_{GS} = 5 \text{ V}, -I_D = 100 \text{ mA}$	R <sub>DS(ON)</sub>	-	7	14	Ω
Thermal Resistance Junction to Ambient Air	R <sub>thJA</sub>	-	-	150 <sup>1)</sup>	K/W
Capacitances at –V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0, f = 1 MHz Input Capacitance Output Capacitance Feedback Capacitance	C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub>	_ _ _	200 30 10		pF pF pF
Switching Times at –I <sub>D</sub> = 200 mA, –U <sub>GS</sub> = 10 V Turn-on Time Fall Time	t <sub>on</sub> t <sub>f</sub>		5 15		ns ns
<sup>1)</sup> Valid provided that leads are kept at ambient temperature at a distance of 2 mm from case.					

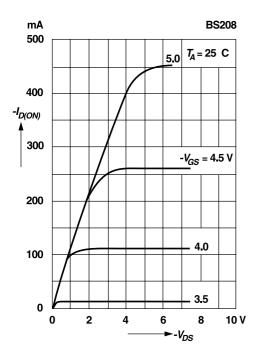


### **RATINGS AND CHARACTERISTIC CURVES BS208**

Admissible power dissipation versus temperature Valid provided that leads are kept at ambient temperature at a distance of 2 mm from case



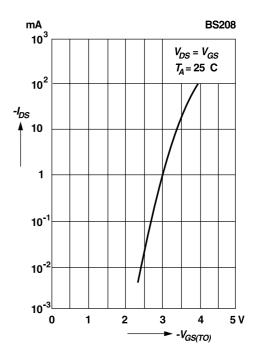
Saturation characteristics Pulse test width 80 ms; pulse duty factor 1%



BS208 Α 2.0  $T_A = 25$  C -*V<sub>GS</sub>* = 9 V 1.6 8 -I<sub>D(ON)</sub> 7 1.2 6 0.8 5 0.4 4 3.5 3 0 0 20 40 60 80 100 V ►-V<sub>DS</sub>

**Output characteristics** Pulse test width 80 ms; pulse duty factor 1%

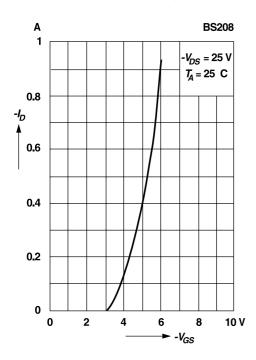
**Drain-source current** versus gate threshold voltage



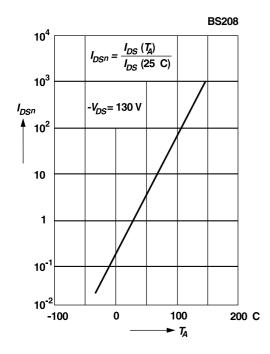
GENERAL **SEMICONDUCTOR**<sup>®</sup>

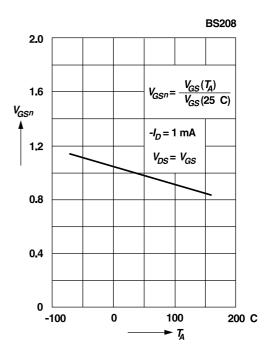
### **RATINGS AND CHARACTERISTIC CURVES BS208**

Drain current versus gate-source voltage Pulse test width 80 ms; pulse duty factor 1%



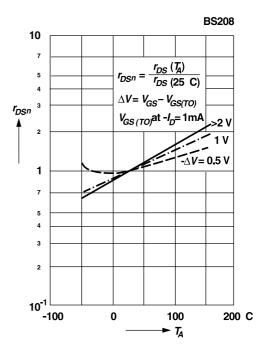
Normalized drain-source current versus temperature





Normalized gate-source voltage versus temperature

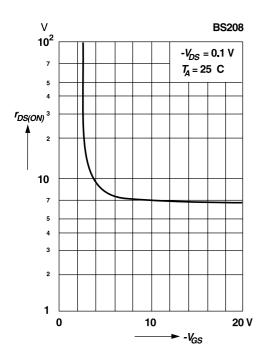
## Normalized drain-source resistance versus temperature



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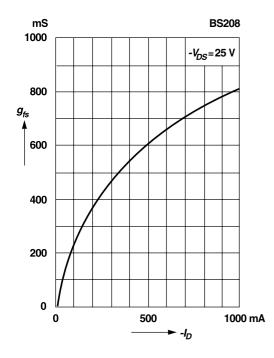
### **RATINGS AND CHARACTERISTIC CURVES BS208**

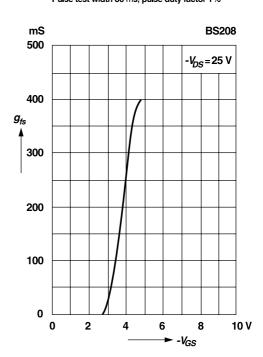
Drain-source resistance versus gate-source voltage



Transconductance versus drain current

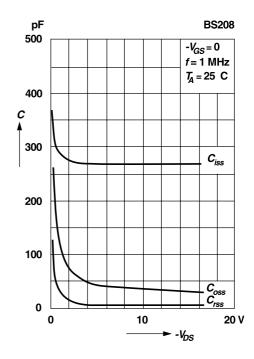
Pulse test width 80 ms; pulse duty factor 1%





Transconductance versus gate-source voltage Pulse test width 80 ms; pulse duty factor 1%

Capacitance versus drain-source voltage



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